

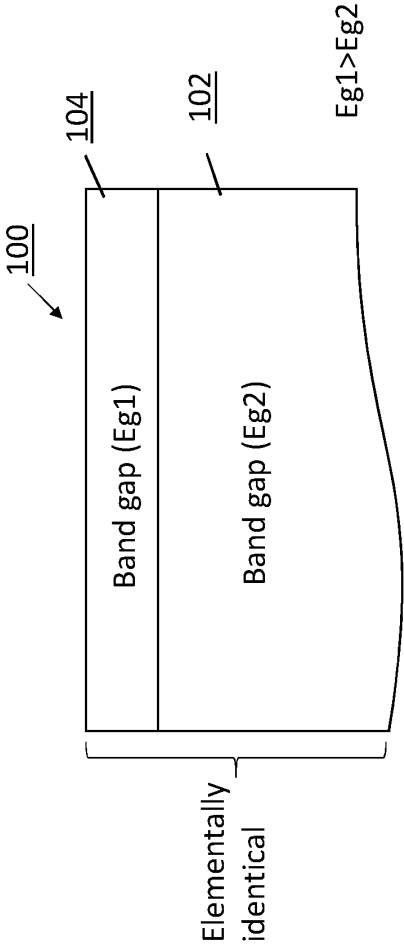


FIG. 1

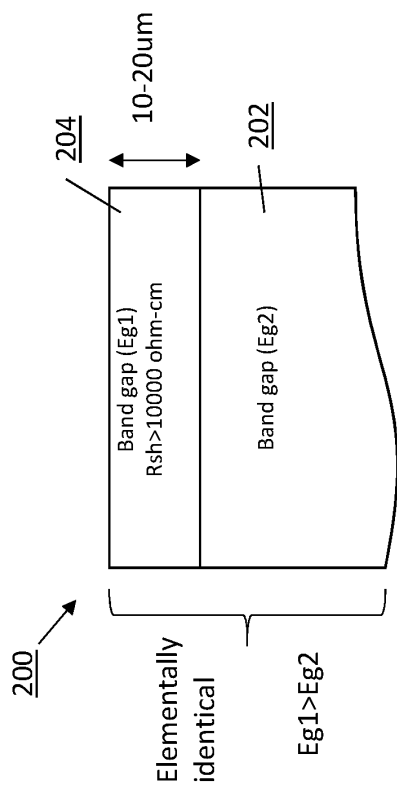


FIG. 2

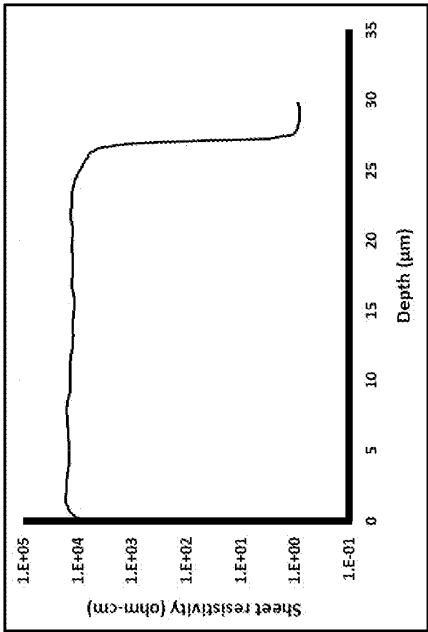


FIG. 3

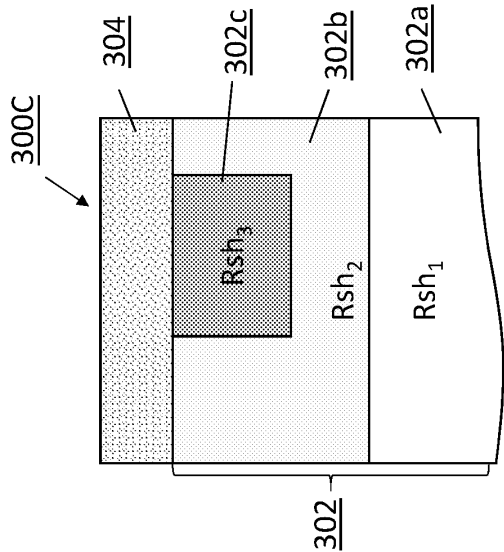


FIG. 6

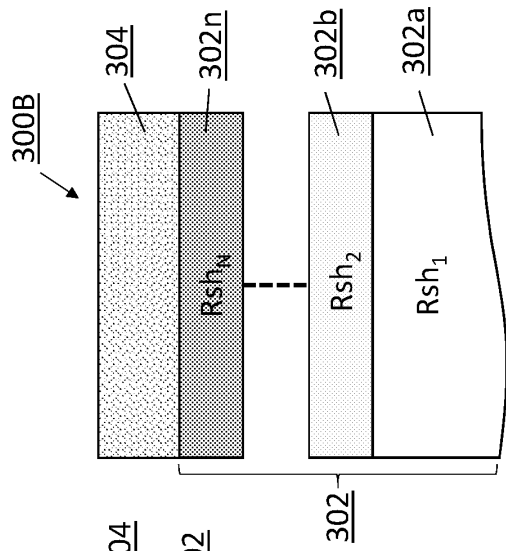


FIG. 5

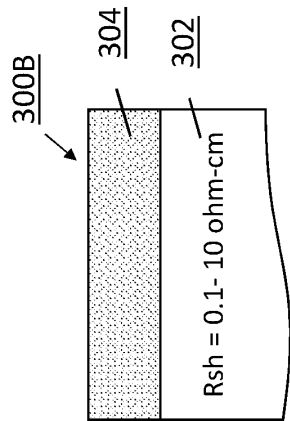


FIG. 4

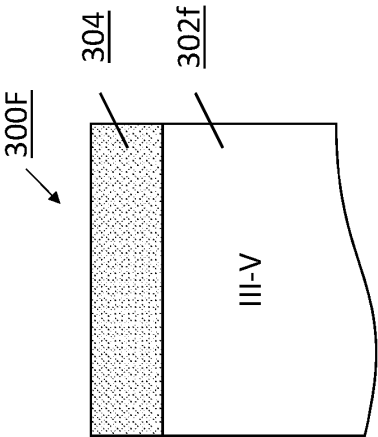


FIG. 9

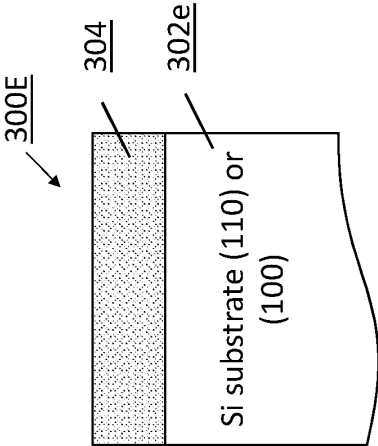


FIG. 8

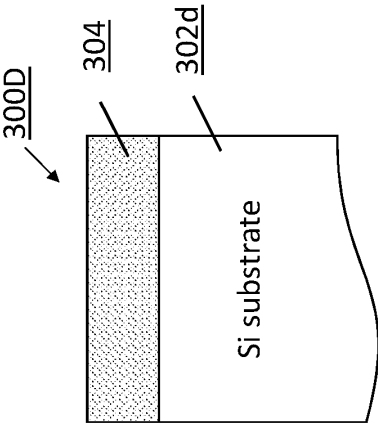


FIG. 7

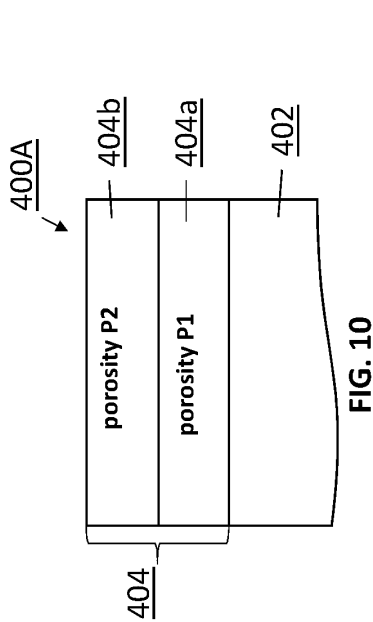


FIG. 10

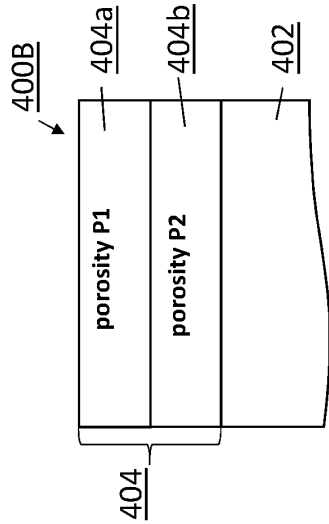


FIG. 11

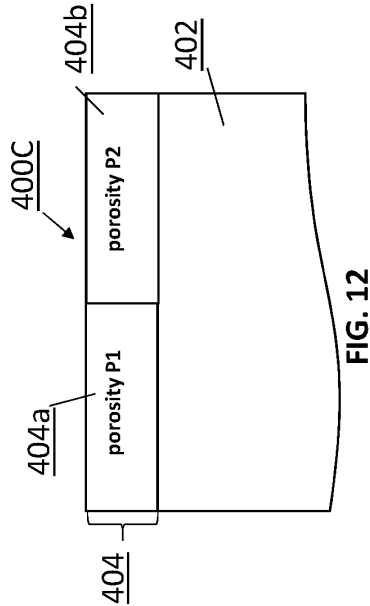


FIG. 12

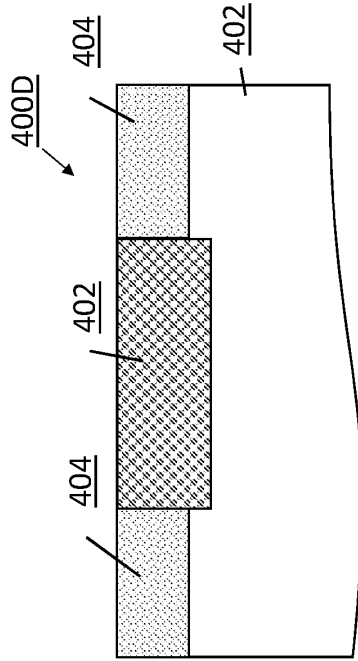


FIG. 13

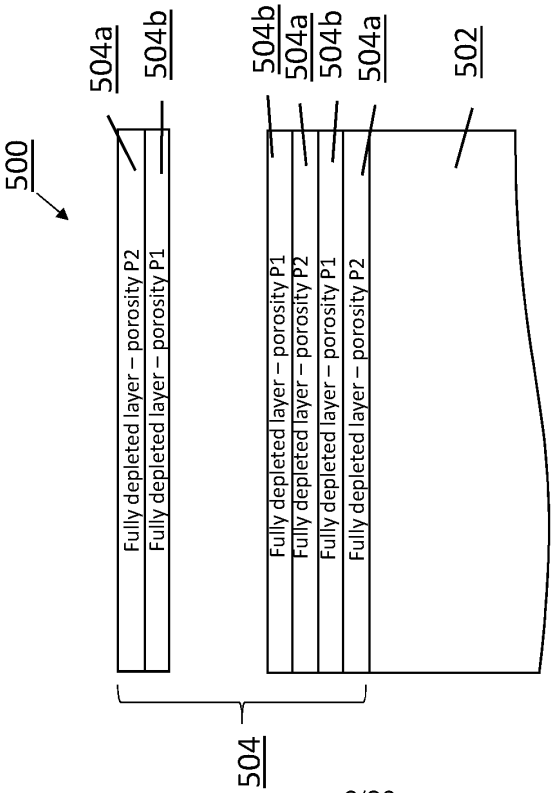


FIG. 14

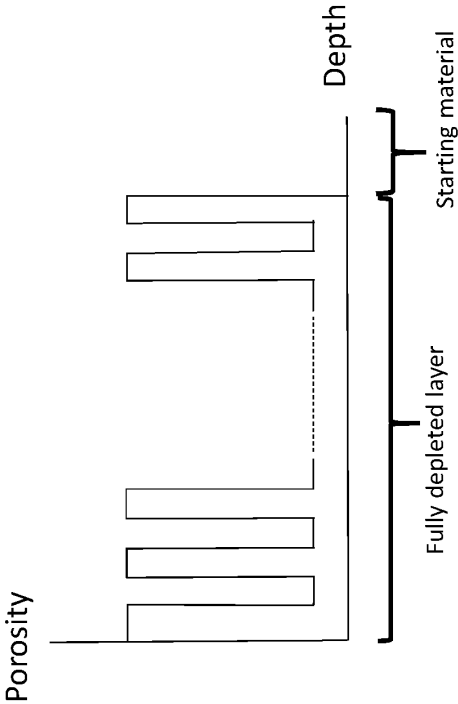


FIG. 15

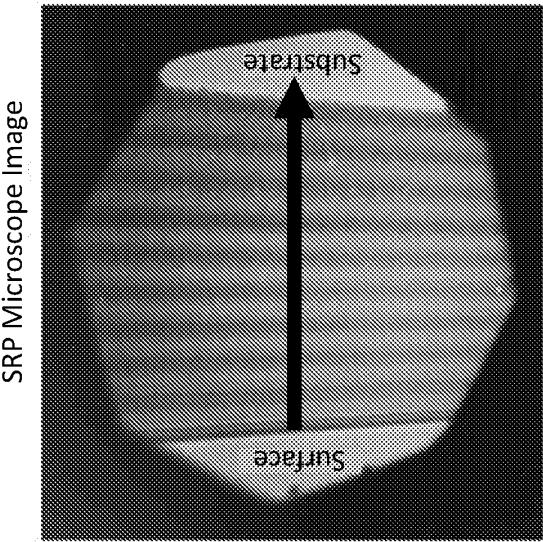


FIG. 16

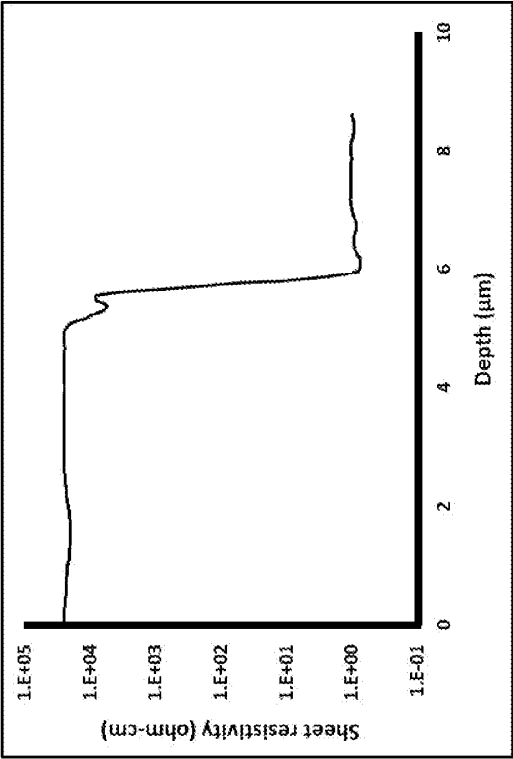


FIG. 17

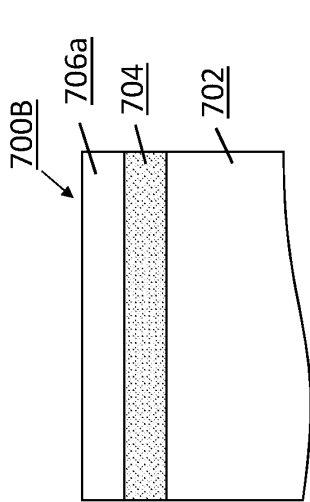


FIG. 19

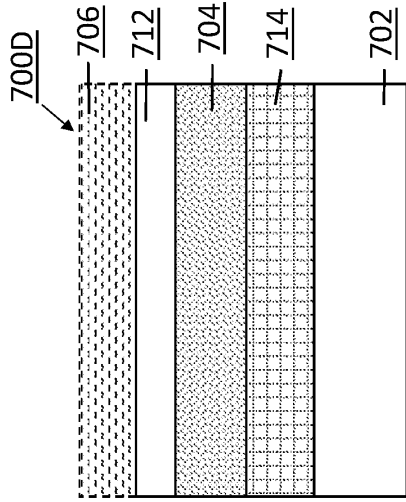


FIG. 21

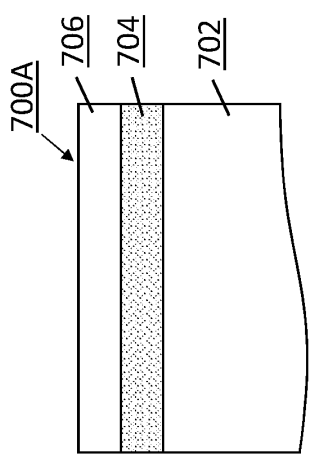


FIG. 18

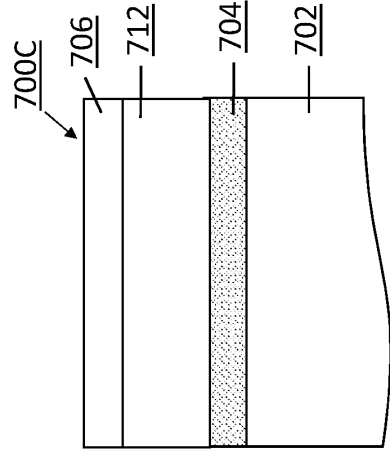


FIG. 20

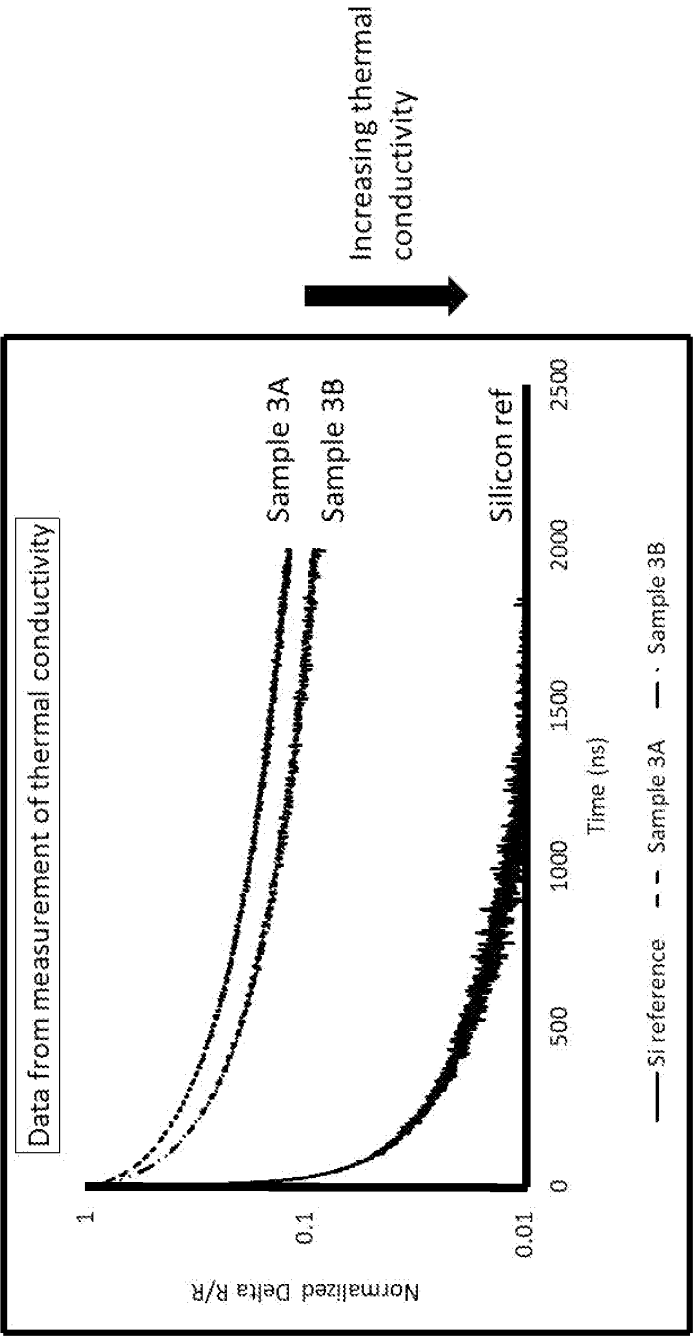


FIG. 22

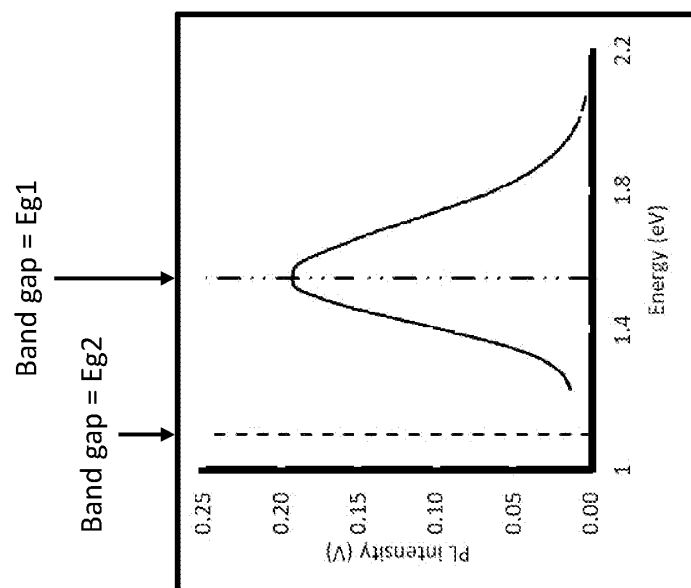


FIG. 23

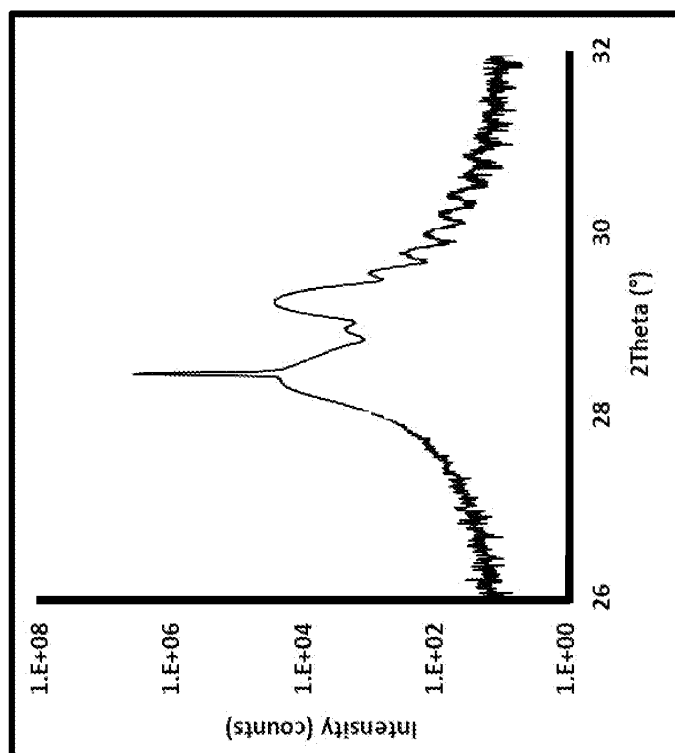


FIG. 25

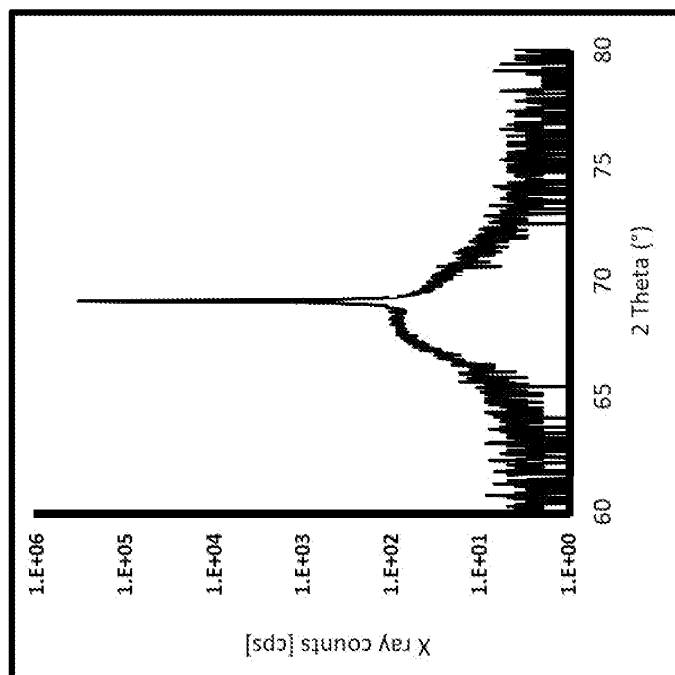


FIG. 24

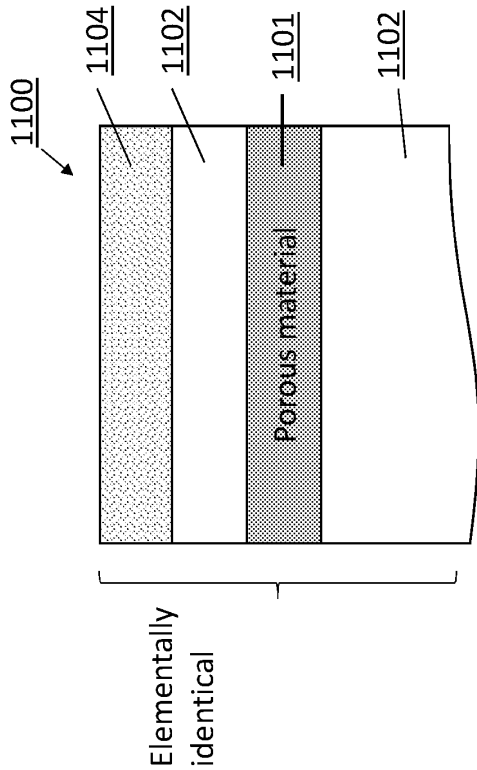
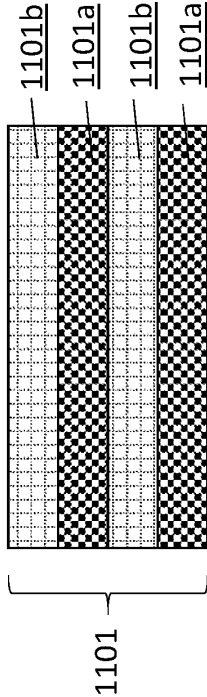
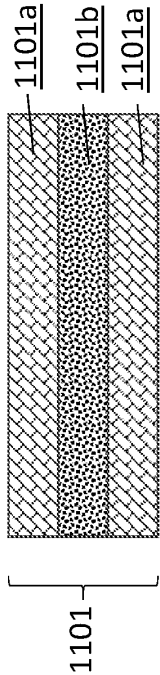


FIG. 26



Hi-Lo periodic structure

FIG. 27



Buried Hi porous region
for wafer separation

FIG. 28

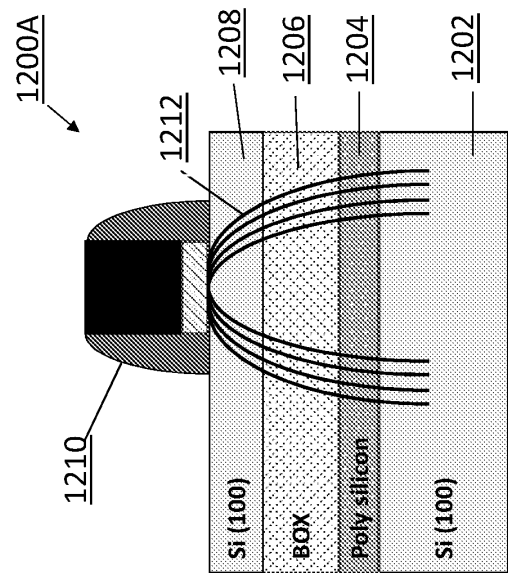
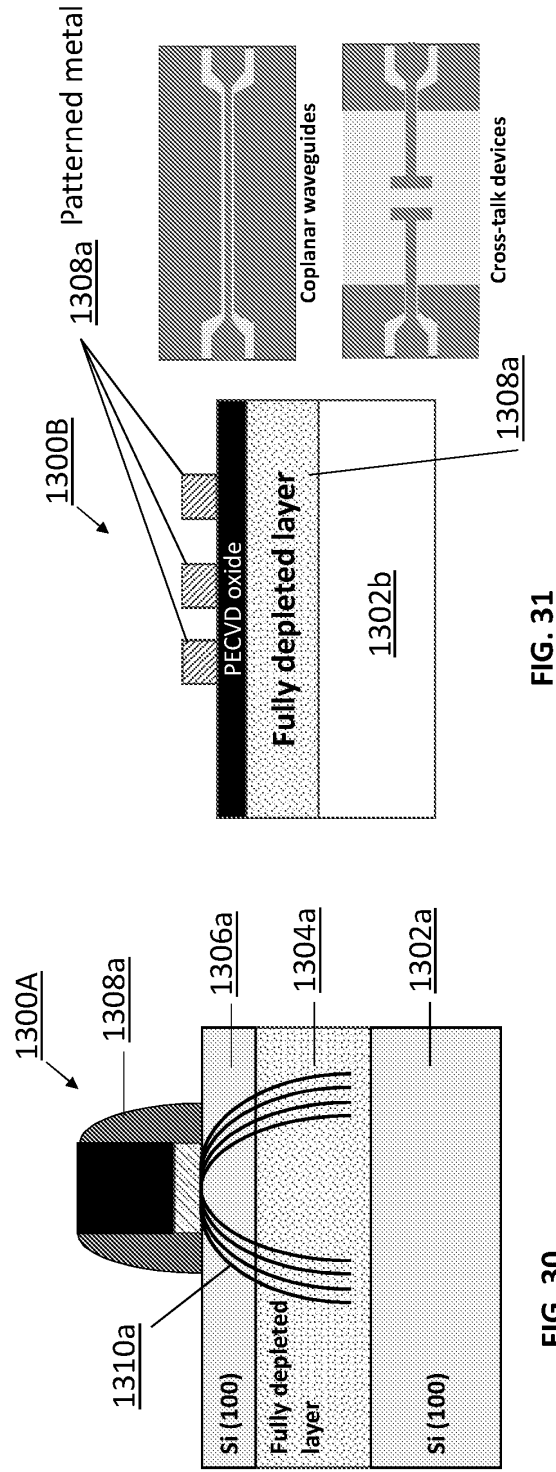


FIG. 29



■ Process 2A ◆ Process 3A, 3B ▲ Process 4A

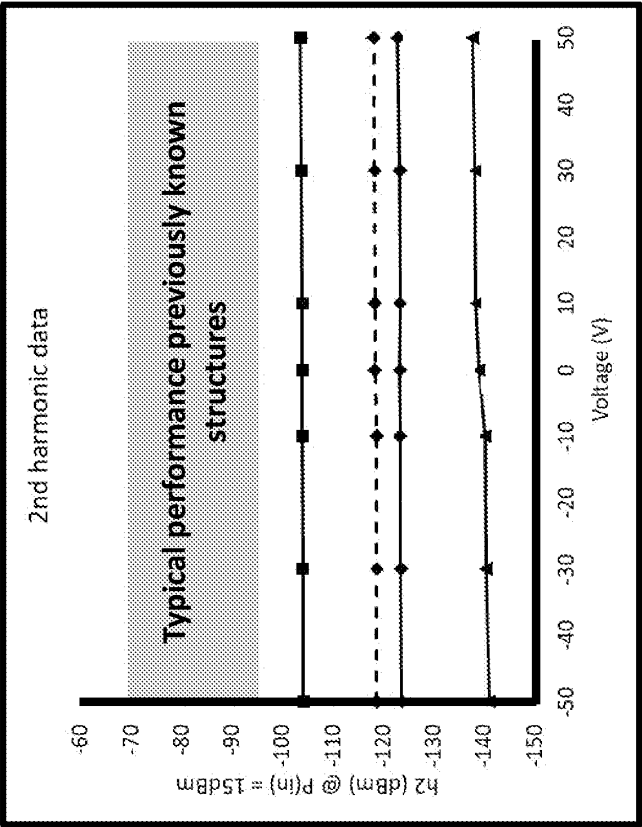


FIG. 32

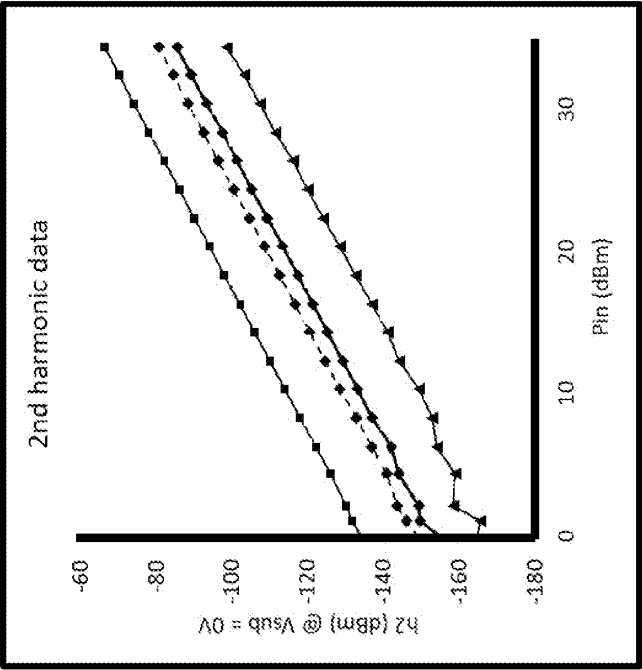


FIG. 33

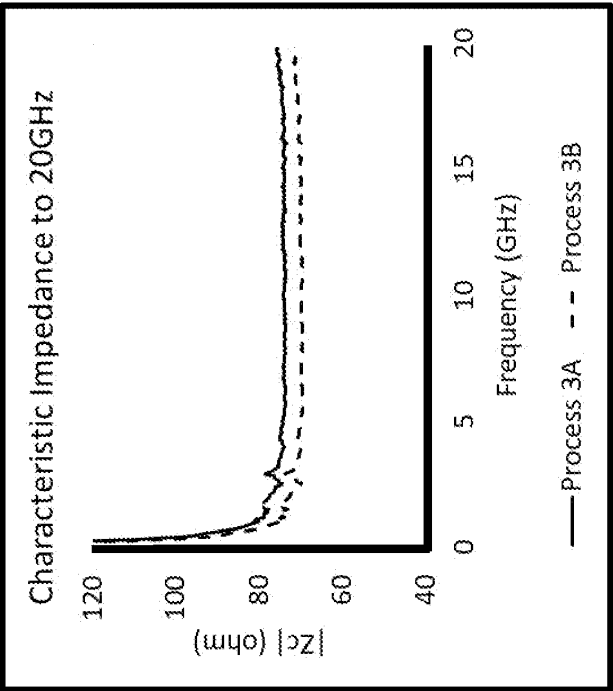


FIG. 35

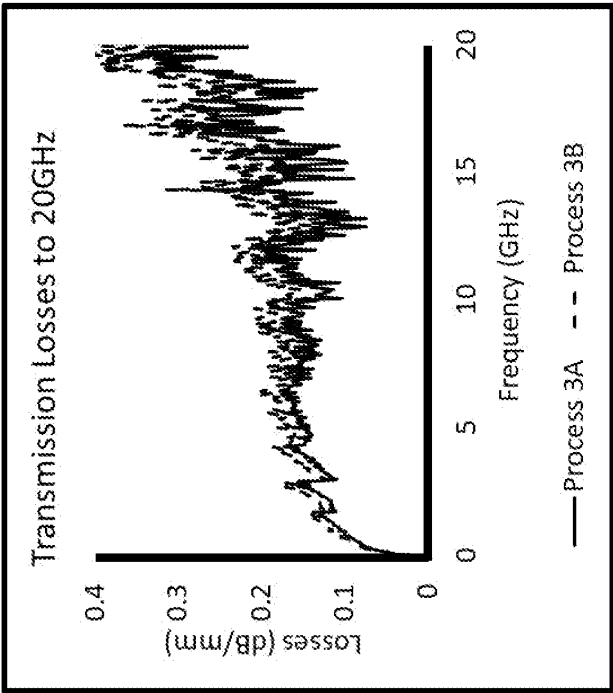


FIG. 34

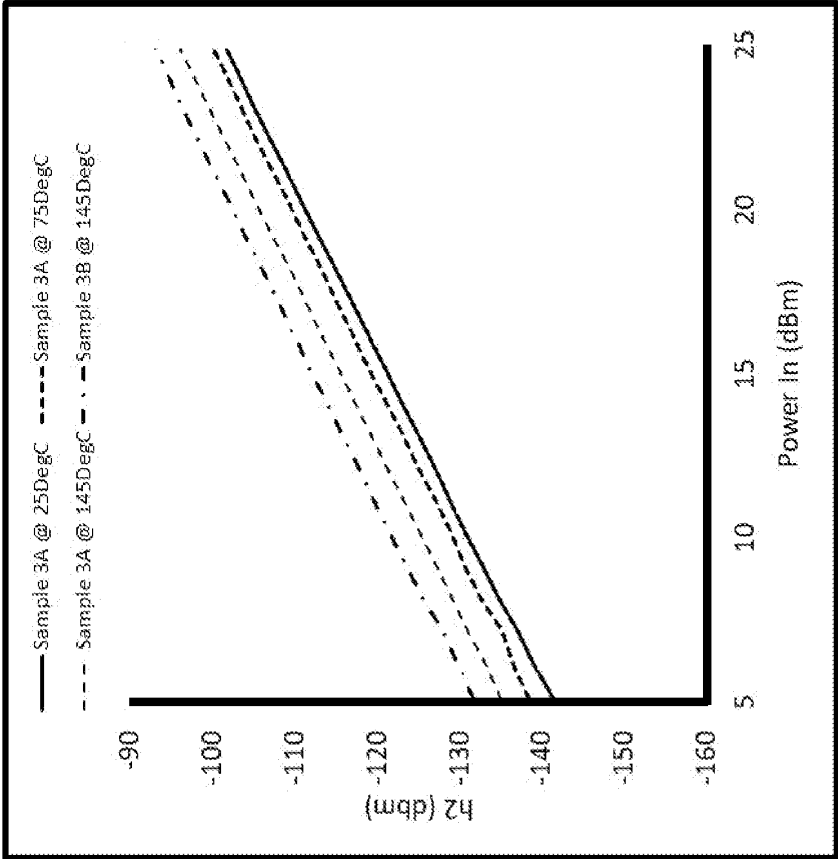


FIG. 36

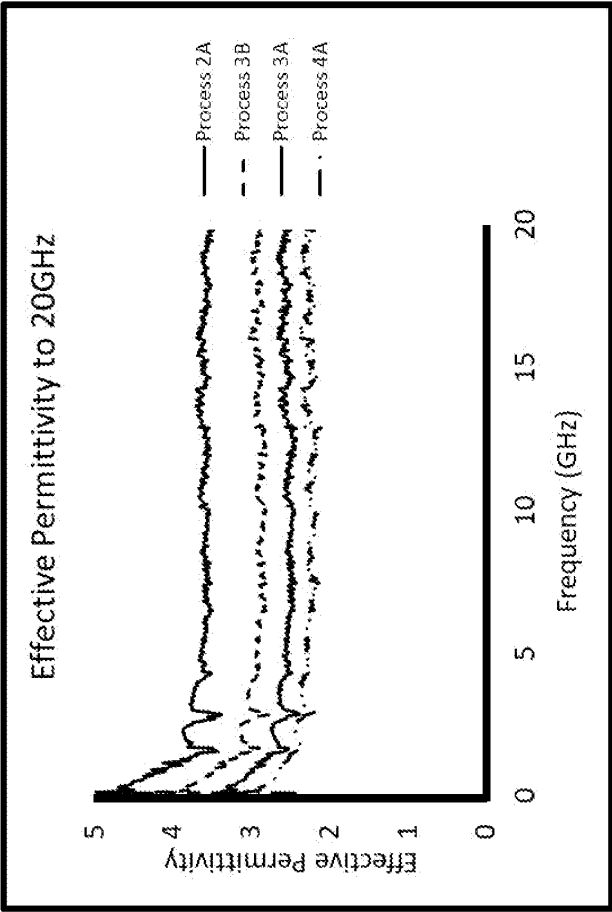


FIG. 37

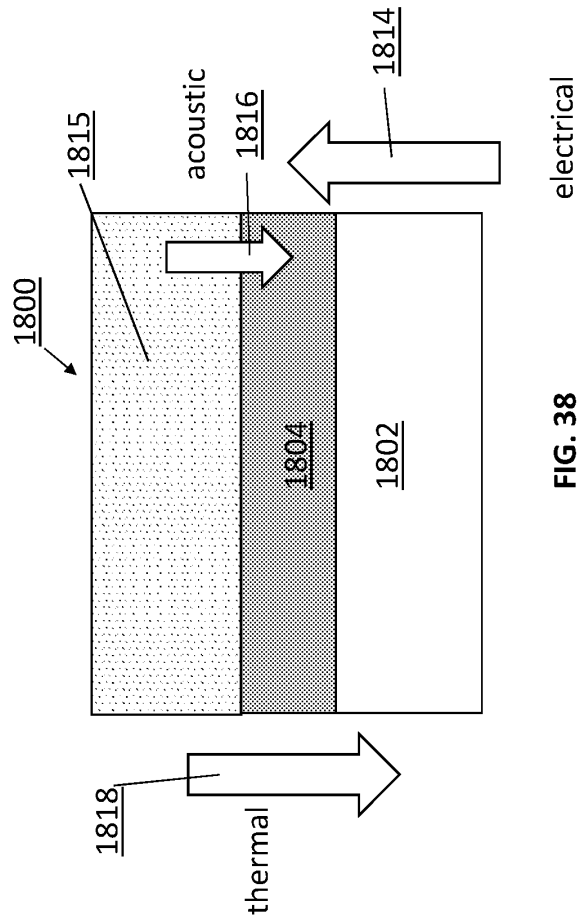


FIG. 38

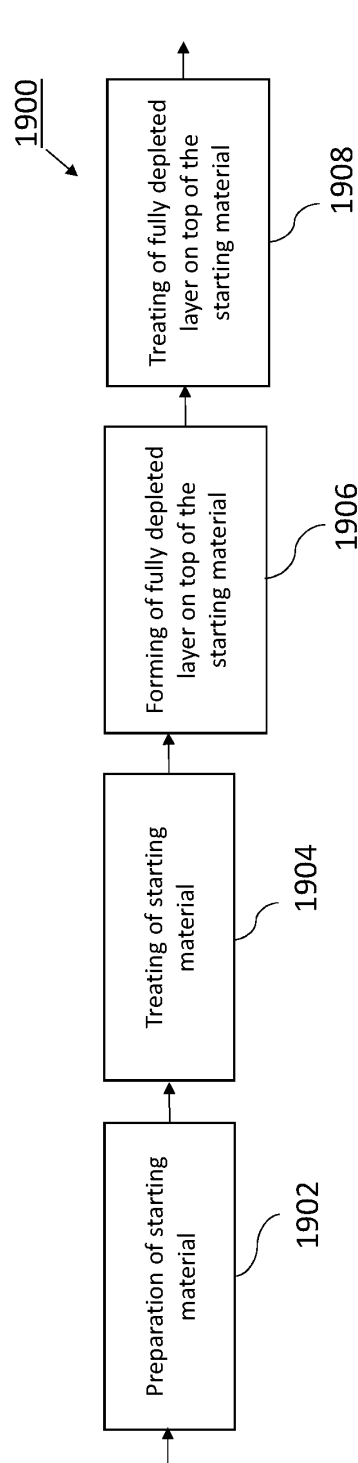


FIG. 39

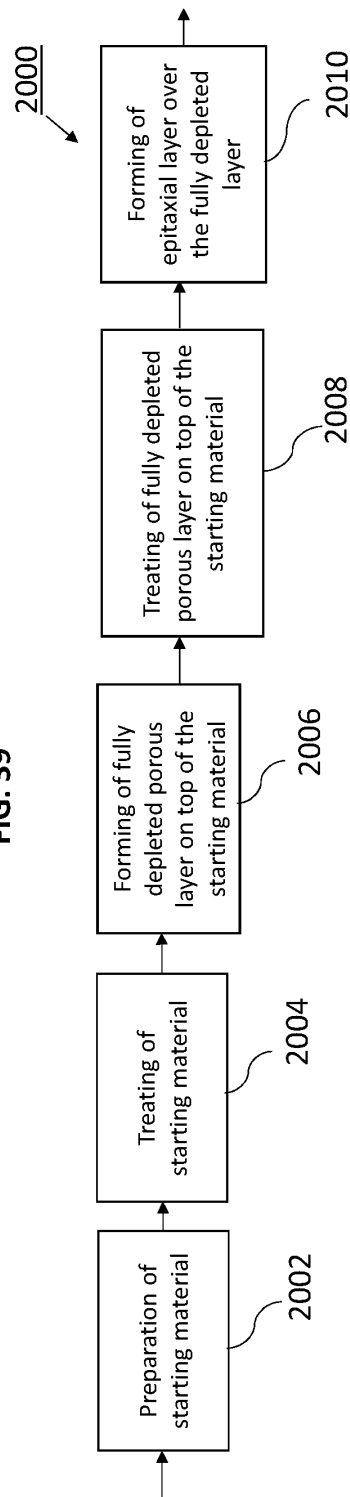


FIG. 40